

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

31.03.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-035my 330x490mm	50200242	35	VS	1	A00 B00
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	381		2	
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		3	
		35	L2		
B-RaS-FR4-DS-1.575mm-035+035-TG150-HF...	50203149	1505		4	
		35	L3		
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	381		5	
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		6	
A-RS Kupferfolie-035my 330x490mm	50200242	35	RS	7	

Thickness after Pressing

B00: 2290 µm Tol+: 240 µm Tol-: 240 µm Dmax: 2530 µm Dmin: 2050 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 2400 µm Tol+: 240 µm Tol-: 240 µm Dmax: 2640 µm Dmin: 2160 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 2407 µm

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